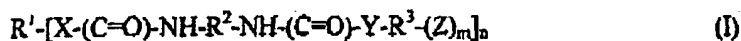


Serial No. 09/868,566

Art Unit: 1712



in which

 $m = 1$  or  $2$ , $n = 2$  or  $3$ ,

$R^1$  is a residue of a polyalkylene glycol after removal of the functional groups (hydroxyl or amino groups),

$R^2$   $[[=]]$  is  $C_{1-14}$  alkyl, aryl, aralkyl (residue of a diisocyanate after removal of the isocyanate groups),

$X, Y$   $[[=]]$  is  $-O-$ ,  $-S-$  or  $-NR^4$ , where  $R^4 = H$  or  $C_{1-4}$  alkyl or phenyl,

$R^3$  is a carbocyclic-aromatic or araliphatic  $m+1$ -functional residue with groups  $Z$  directly attached to the an aromatic ring and  $Z$   $[[=]]$  is  $-OH$  or  $-NHR^4$  (residue of a polyphenol or aminophenol after removal of the functional groups).

B1

7 ~~21~~. (Previously entered) The composition claimed in claim ~~18~~, wherein component B) is dissolved in a liquid polyepoxide.

8 ~~22~~. (Previously entered) The composition claimed in claim ~~18~~, wherein component B) is reacted with a stoichiometric excess of a polyepoxide.

9 ~~23~~. (Currently amended) The composition claimed in claim ~~18~~ further comprising wherein  
D) comprises a latent hardener selected from the group consisting of dicyanodiamide, guanamines, guanidines, aminoguanidines, solid aromatic diamines and mixtures thereof and optionally a hardening accelerator; and

~~E) optionally plasticizers, reactive diluents, rheology aids, fillers, wetting agents, antiagers and stabilizers.~~

10 ~~24~~. (Previously added) A cured composition of claim ~~18~~ having an impact peel energy of at least  $5 \text{ J at } -20^\circ\text{C}$  (to ISO 11343).

11 ~~25~~. (Previously added) The production of composite materials, potting compounds in the electrical and electronics industries and die-attach adhesive for the production of circuit boards in the electronics industry wherein the adhesive comprises the composition of claim ~~24~~. <sup>10</sup>

~~26~~. (Cancelled)

27. (Currently amended) The method A-process for hardening a composition of claim ~~26~~ <sup>15</sup> which comprises heating the composition to a temperature of  $80^\circ\text{C}$  to  $210^\circ\text{C}$ .

28. (Currently amended) A process method for bonding members selected from the group